Hybrid 6p70 Traveler

June 19, 2000

1 Connectivity

Repairs on shorts:
Fixes for opens:
PRD1 and PRD2 both open on hybrid. Fixed with wires to solder field from other solder field.

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 6P70 has die: 193-017 193-018 247-117 193-021 193-024 193-026

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 6p70 classification info. Created 09:19:56 06/15/00

Hybrid 6p70 quality: fair
Chip classification: good fair fair good good fair
Bad channels (chip-channel): 5-52 5-62
Bad cells: none
Random bad capacitors (chip-cell-channel): 1-16-124 2-27-93 2-29-93
   2-40-92 2-40-93 2-7-93
Channels at pedestal needed for DCMS: 28.5 30.7 33.7 30.7 34.6 29.6
```

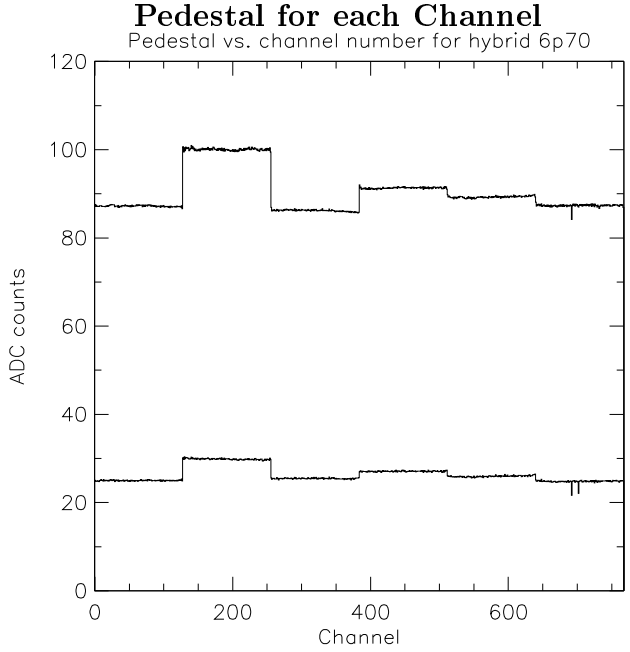
4 Comments

Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

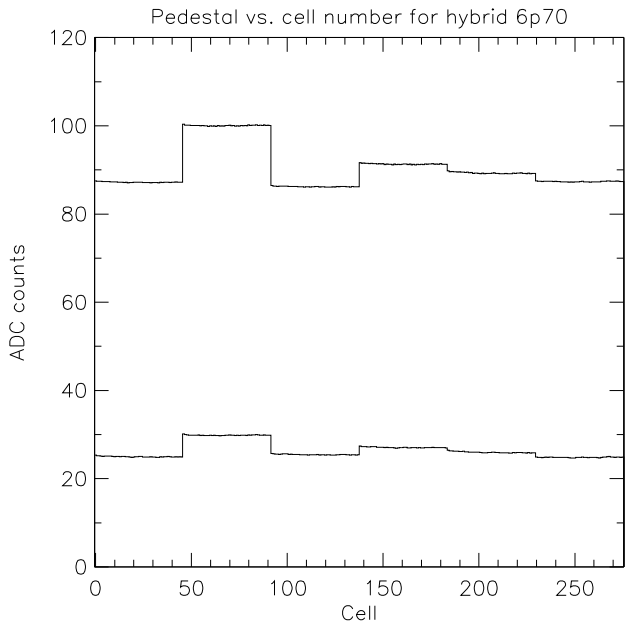
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

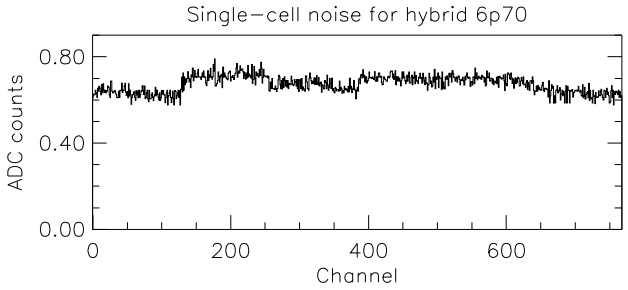
Pedestal vs. Pipeline Cell ID

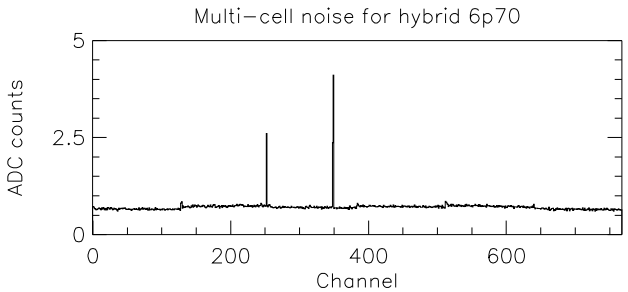


6 Noise

The following plots show the single-cell and multi-cell RMS noise:

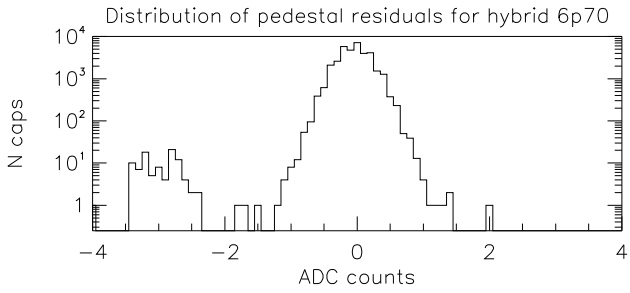
RMS Noise

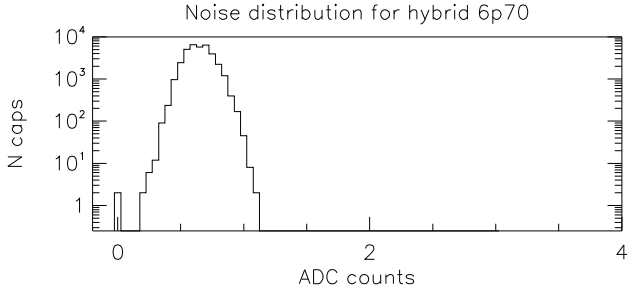




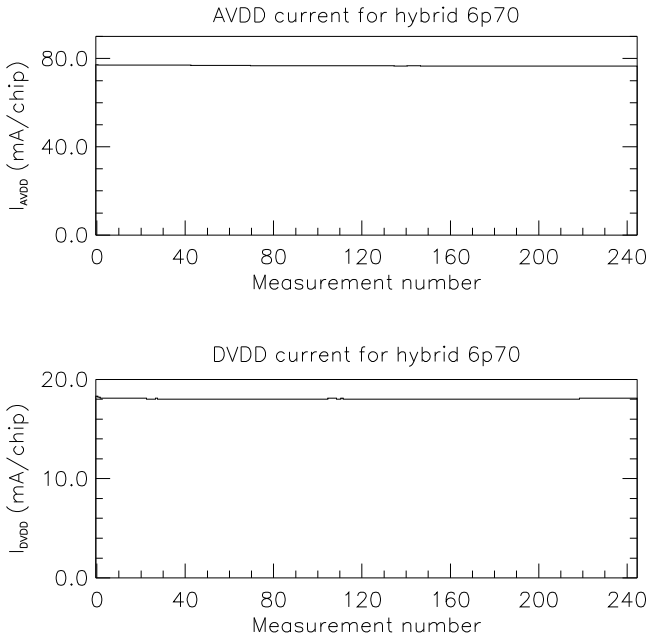
The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise





7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in